

The logo for DIGITIMES, featuring the word "DIGITIMES" in a bold, white, sans-serif font. The letter "D" is stylized with a white outline and a white fill, and the "I" is also stylized with a white outline and a white fill. The rest of the letters are solid white. The logo is set against a solid orange rectangular background.

(Taiwan)

Heterogeneous integration technology continues to evolve EVG talks about hybrid bonding and NIL trends – September 10, 2023

異質整合技術不斷演進 EVG談混合鍵合、NIL趨勢

- 康瓊之 / 台北
- 2023-09-11

人工智慧 (AI) 帶動伺服器、高階晶片及先進封裝需求，作為次世代先進封裝技術的3D晶片也成為潛力之星，混合鍵合 (hybrid bonding) 技術扮演關鍵角色，晶圓代工三大龍頭台積電、三星電子 (Samsung Electronics)、英特爾 (Intel) 也都看好其未來...

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